

GAM 320 視覺對位全自動PCB分板機

Vision Added Automatic PCB Separator

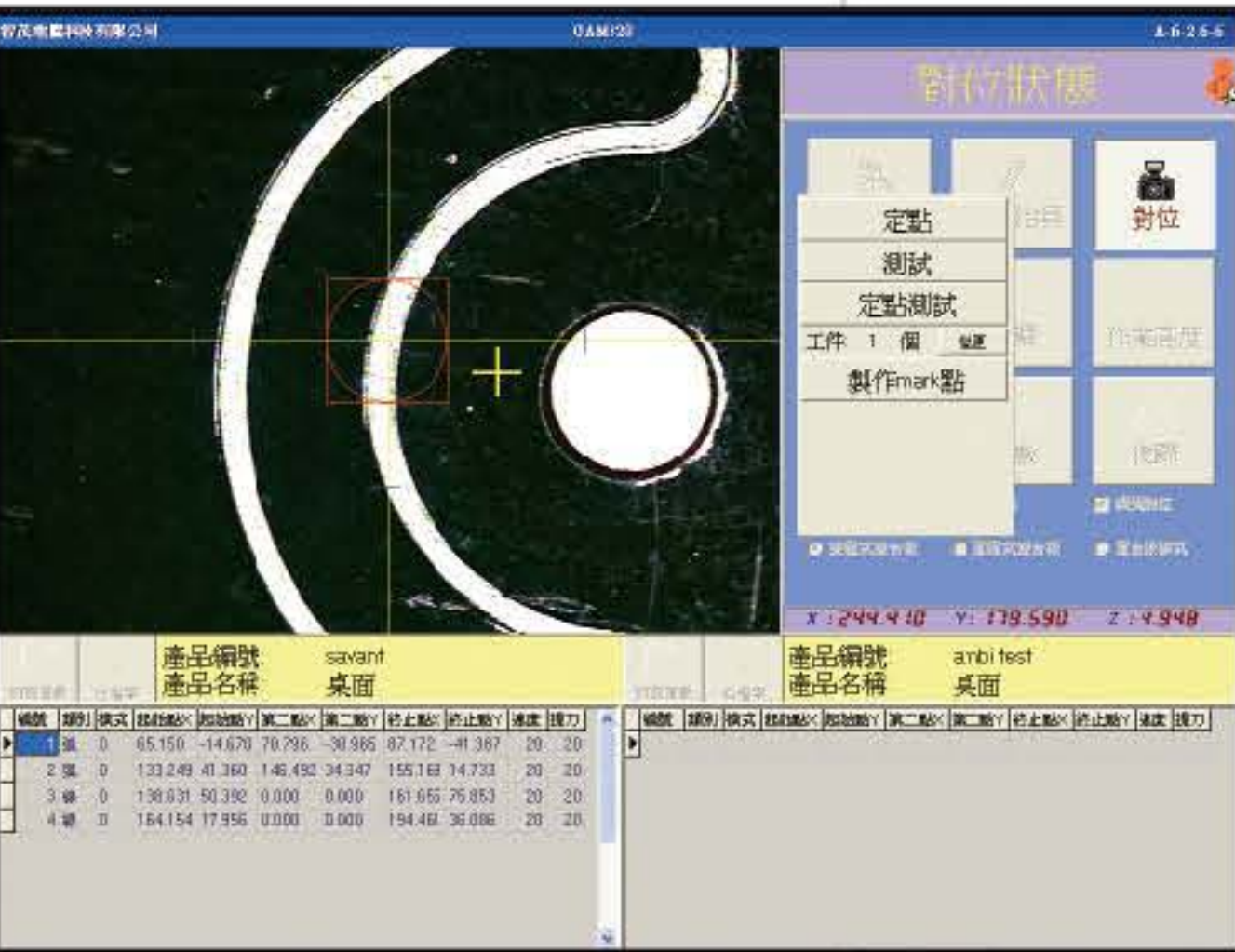
產品特性 (FEATURES)

- 全系列配置高速CCD視覺自動校正系統，大幅提高切割精度及操作效率。
- 採用高速主軸做PCB之切割分板，分割應力小、精度高，且適用任何形狀之電路板。
- 雙檯面運動，可同時執行分板切割及電路板置放，提高作業效率。
- 專利高效率集塵裝置，低噪音提高效率，維護清潔容易。
- Windows視窗作業系統，安全穩定、易學易用。
- Equip high speed CCD with automatic vision alignment system at set, great improve the precision of cutting precision and operation efficiency.
- Use high-speed main shaft to cut PCB, less cutting stress, high precision, and apply to any form of PCB.
- Dual tables motion to carry out PCB cutting and placing at the same time, improve operation efficiency.
- High efficiency patent dust-collector, low noise, easy clean and maintain.
- Window operation system not only safe and stable but also easy to learn and use.



編輯畫面 Operational Vision

- 圖示化視窗操作畫面，易學易用。
- 螢幕上直接做分板程式之編輯設定。
- Diagrammatic window operating pages, easy to learn and operate.
- Directly edit the cutting programming on screen.



切割設定 System Setting

- 提供圖示化機器微調校正。
- 設定分板切割之相關參數。
- Provides the fine tuning revise by diagrammatic machine.
- Set the related parameters of cutting.



維護程式 Maintenance program

- 提供圖示化機器微調校正。
- 視窗作業環境易學易操作。
- Provides the fine tuning revise by diagrammatic machine.
- Windows Operational Environment: Easy to learn.



機台應用 (APPLICATION)

- 全系列配置高速CCD視覺對位補正裝置，特別適合高精密及高產能之PCB分板作業。
- 適合手機、數位相機、GPS、PDA及MODULE等各種小塊多連板之PCB分板。
- 加大尺寸適用數位電視、PC主機、工作站、伺服器等大型電路板之分板加工。
- 可選用標準治具或專用治具做分板切割之輔助提高產能。
- 利用雙工作平台放置工件，減少等待時間、增加產能。
- Equip high speed CCD with automatic vision offset at set, special design for high precision and production PCB cutting process.
- Apply to small linking PCB such as cell-phone, digital camera, GPS, PDA and MODULE cutting processing.
- Extended size applies to those large PCB of digital TV, PC mainframe, workstation, and server cutting process.
- Choice standard jig or special purpose jig to aid in PCB cutting to increase production.
- Using dual tables to place work piece, increase production and less waiting time.



銑刀機構 Mill equipment

- 採用60000轉進口高速精密主軸。
- 切割應力小、板邊平滑、精密度高。
- 使用左旋銑刀，配合下吸式集塵機。
- Z軸具備自動補償設定，可自動調整銑刀深度。
- Use high speed precision spindle, 60,000 RPM.
- Less cutting stress smooth edge high precision.
- Use left mill to coordinate down dust-collector.
- Z axis equips auto offsetting, mill depth is adjustable.



集塵設備 Dust-collector

- 採用高效率馬達及風扇，噪音低、集塵效率佳。
- 採用直筒式濾袋，切割後之粉塵及碎片經拍打後集中收集。
- 具備風口切換裝置，增加集塵風量。
- Adapt to high effective motor and fan, will reduce noise and increase dust-collecting efficiency.
- Adapt roof of filter bag to gather up collecting powder dust and broken piece after cutting.
- Equip switch of air-gap to increase airflow of dust-collecting.

GAM 30 V-CUT分板機

V-CUT PCB Separator



- 圓刀切割減少分板壓力，防止焊點龜裂。
- 特殊切割刀具，確保PCB分割面之平滑度。
- 多段速度及距離可調，可快速更換不同PCB尺寸之分板。
- 可切割PCB之最大尺寸：400X150mm。
- 可切割PCB之最大厚度：3.2mm。
- Round knife cut to reduce cutting stress and prevent chapping in solder points.
- Special cutting tools to ensure smooth cutting of PCB surface.
- Multi-speed setting and gap is adjustable, to change different PCB size quickly.
- Acceptable cutting size of PCB : 400X150mm (max.)
- Acceptable cutting thickness of PCB : 3.2mm (max.)